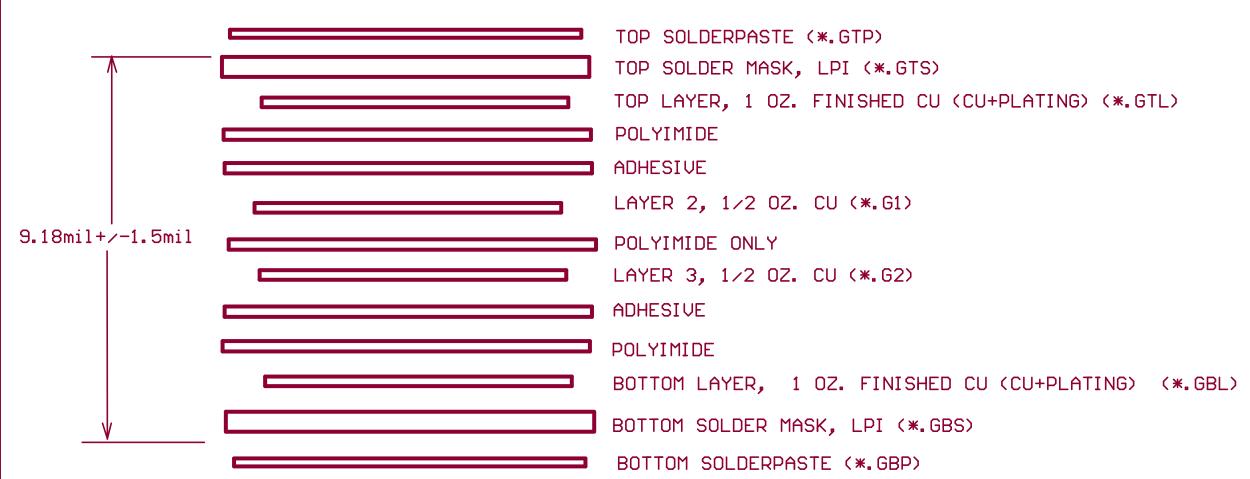


NOTES:

- 1. FABRICATE AND INSPECT PER IPC6011 AND IPC-6013, CLASS 3, TYPE 3.
- 2. MINIMUM TRACE WIDTH IS 4 MIL, MINIMUM CONDUCTOR SPACING IS 4 MIL, MINIMUM PLATED HOLE DIAMETER IS 3.3 MIL.
- 3. LAYER TO LAYER REGISTRATION SHALL BE WITHIN 2 MIL.
- 4. SOLDER MASK TO LAYER REGISTRATION SHALL BE WITHIN 2 MIL.
- 5. HOLE SIZE TOLERANCE, +2/-3 MILS. HOLE POSITION TOLERANCE SHALL BE WITHIN 2 MILS.
- 6. COPPER PLATE ON WALLS OF PLATED HOLES SHALL BE A MINIMUM OF 0.8 MIL.
- 7. LPI SOLDER MASK TOP AND BOTTOM SIDE OVER BASE COPPER (COLOR GREEN).
- 8. GOLD PLATE EXPOSED COPPER, ELECTROLESS NICKEL (120-360 MICRO-INCH), IMMERSION GOLD (2-6 MICRO-INCH).
- 9. MATERIALS AND PROCESSES MAY BE CHANGED WITH PRIOR Z-POWER APPROVAL.
- 10. OUTLINE ROUTE TOLERANCE SHALL BE +/- 3MILS.

LAYER STACK-UP



Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape
0	8	0.085mm (3.35mil)	PTH	Round	Layer 3 - Layer 4 (bottom)	Via	Rounded
	20	0.085mm (3.35mil)	PTH	Round	Layer 1 (Top) - Layer 4 (bottom)	Via	Rounded
	28 Total						

Drill Drawing.

